

DWG. NO. SD-53398-034

F

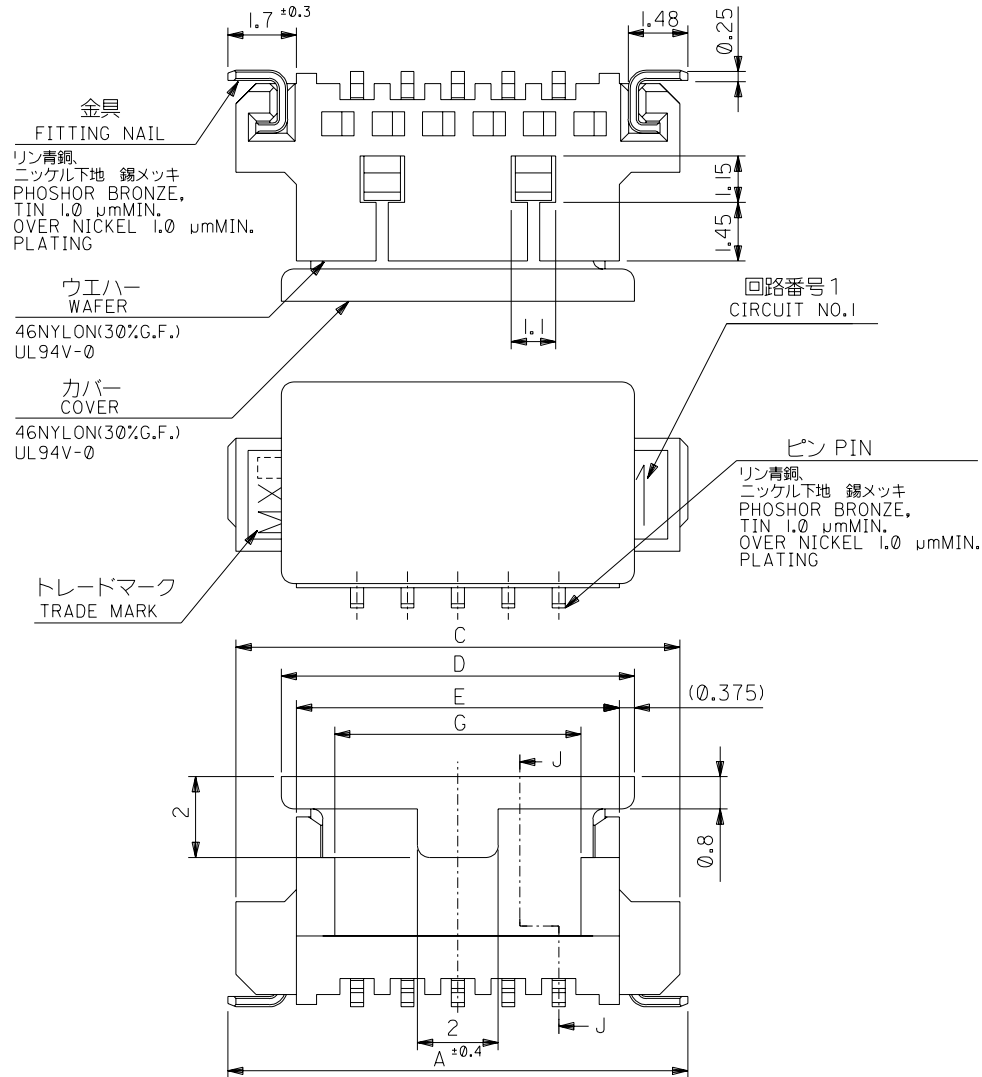
E

D

C

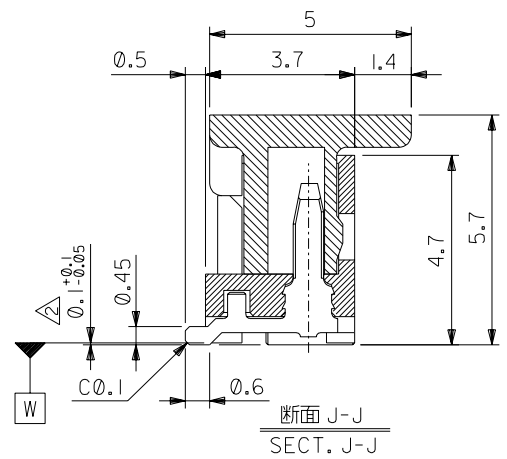
B

DO NOT SCALE DRAWING



NOTES

1. 嵌合相手: 51021 シリーズ MATE WITH : 51021 SERIES
2. 水平面上において、ウェハー底面 **W** とソルダーテール及び
フィッティングネイル底面とのズレ量を示す。
MISALIGNMENT OF SOLDER TAIL & FITTING NAIL FROM **W**
3. 偶数極にのみ適用。APPLY EVEN CIRCUIT PRODUCTS.
4. 本製品は 53398-**-20 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53398-**-20.



17.35	18.05	19.25	20	22.25	16.25	22.3	53398-1429	14
14.85	15.55	16.75	17.5	19.75	13.75	20.15	53398-1229	12
9.85	10.55	11.75	12.5	14.75	8.75	15.15	53398-0829	8
8.6	9.3	10.5	11.25	13.5	7.5	13.9	53398-0729	7
7.35	8.05	9.25	10	12.25	6.25	12.65	53398-0629	6
6.1	6.8	8	8.75	11	5	11.4	53398-0529	5
4.85	5.55	6.75	7.5	9.75	3.75	10.15	53398-0429	4
3.6	4.3	5.5	6.25	8.5	2.5	8.9	53398-0329	3
2.35	3.05	4.25	5	7.25	1.25	7.65	53398-0229	2
G	F	E	D	C	B	A	MATERIAL NO.	CIRCUITS

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	RELEASED '04/02/12 EC NO. J2004-2404 DRWN: Y.SAKIYAMA CHK: M.SASAO APPR: M.SASAO	DESCRIPTION	MATERIAL 材料	SEE DRAWING	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		SCALE —	DESIGN UNITS ☒ mm ☐ INCH	 THIRD ANGLE PROJECTION	☐ mm INCH	☐ INCH mm	☒ mm ONLY	REVISE ON CAD ONLY
						10 UNDER 未満		±0.2	DRAWN BY & DATE Y.SAKIYAMA '04/02/12		TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT (ST.) WITH COVER -LEAD FREE-					
						10 OVER 以上 30 UNDER 未満		±0.25	CHECKED BY & DATE M.SASAO '04/02/12							
						30 OVER 以上		±0.3	APPROVED BY & DATE M.SASAO '04/02/12		 MOLEX INCORPORATED					
WIRE RANGE 適用電線範囲	—	ANGLE 角度		CAD FILENAME SD-53398-034.S01	MATERIAL NO. SEE CHART	DRAWING NO. SD-53398-034	SHEET NO. 1 OF 2									
				0	REV	INS. RANGE 被覆外径	—	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.								SIZE B

A

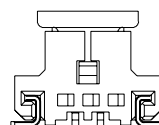
SD-53398-034.S01

E

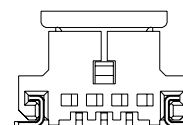
D

C

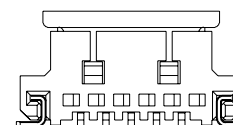
B



2極
2 CKT.



3極
3 CKT.



4極以上
OVER 4 CKT.

△ ロック形状図

NOTES

- △ ロック窓は、2, 3極は1ヶ所、4極以上は2ヶ所とする。
LOCKING WINDOW : ONE PLACE FOR 2&3 CKTS.
TWO PLACES FOR MORE THAN 4 CKTS.

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	RELEASED 04/02/12 EC NO. J2004-2404 DRWN: Y.SAKIYAMA CHK: M.SASAO APPR: M.SASAO	DESCRIPTION	MATERIAL 材料 SEE NOTES	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE —/—	MODEL NO. 53398-**-29	DIMENSIONS: ☐ mm INCH ☐ INCH ☒ mm ONLY	SHT REV
							10 UNDER 未満	±0.2	DESIGN UNITS ☒ mm ☐ INCH	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY
							10 OVER 以上	±0.25	DRAWN BY & DATE Y.SAKIYAMA 04/02/12	TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT (ST.) WITH COVER -LEAD FREE-	
							30 UNDER 未満	±0.25	CHECKED BY & DATE M.SASAO 04/02/12		
							30 OVER 以上	±0.3	APPROVED BY & DATE M.SASAO 04/02/12	MOLEX	
							WIRE RANGE 適用電線範囲		CAD FILENAME SD-53398-034.S02	MATERIAL NO. SEE CHART	SHEET NO. 2 OF 2
					REV	INS. RANGE 被覆外径			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.		SIZE B

